


PCN Number:	20231031008.1		PCN Date:	October 31, 2023	
Title:	Qualification of RFAB using qualified Process Technology and Die Revision for select devices				
Customer Contact:	Change Management team		Dept:	Quality Services	
Proposed 1st Ship Date:	Jan 31, 2024		Estimated Sample Availability:	Dec 1, 2023*	
*Sample requests received after December 1, 2023 will not be supported.					
Change Type:					
<input type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material	
<input type="checkbox"/> Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process	
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification of RFAB using the qualified process technology (TIB) for the selected devices listed below in the product affected section.					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
CFAB	J13	200 mm	RFAB	TIB	300 mm
The die was also changed as a result of the process change.					
Qual details are provided in the Qual Data Section.					
Reason for Change:					
Continuity of supply.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Fab Site Information:					
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
CFAB	CU3	CHN	Chengdu		
RFAB	RFB	USA	Richardson		
Die Rev:					
Current		New			
Die Rev [2P]	Die Rev [2P]				
B	A				
Sample product shipping label (not actual product label)					
 <p> TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750 </p> <p> (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0000017 (20L) CS0: SHE (21L) CC0:USA (22L) AS0: MLA (23L) AC0: MYS </p>					

Product Affected:

OP07CDR

OP07CP

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: OP07CDR	Qual Device: OP07CP	QBS Product Reference: OP07CDR	QBS Package Reference: NE5532P	QBS Package Reference: TS12A4514P	QBS Package Reference: UCC37322P	QBS Process Reference: LM2902BQPWRQ1	QBS Process Reference: TL431BQDBZR	QBS Package Reference: CD4093BQM96Q1	QBS Package Reference: TLC5916QDRQ1	QBS Package Reference: LM358BIDR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-	-	3/231/0	3/231/0	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	1/77/0	3/231/0	-	-	3/231/0	3/231/0	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	-	-	-	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	-	3/231/0	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	1/77/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	-	3/231/0	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	1/77/0	3/231/0	-	-	-	-	1/77/0
HTOL	B1	Life Test	150C	300 Hours	-	-	1/77/0	3/231/0	-	-	-	3/231/0	-	-	-
HTOL	B1	Life Test	150C	408 Hours	-	-	-	-	-	-	3/231/0	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	-	3/2400/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/135C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	-	-	3/66/0	3/66/0	-
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	-	-	3/66/0	-	3/66/0	-	-	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	1/3/0	-	-	-	-	-	-	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	-	-	3/9/0	-	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: OP07CDR	Qual Device: OP07CP	QBS Product Reference: OP07CDR	QBS Package Reference: NE5532P	QBS Package Reference: TS12A4514P	QBS Package Reference: UCC37322P	QBS Process Reference: LM2902BQPWRQ1	QBS Process Reference: TL431BQDBZR	QBS Package Reference: CD4093BQM96Q1	QBS Package Reference: TLC5916QDRQ1	QBS Package Reference: LM358BIDR
ESD	E2	ESD CDM	-	250 Volts	-	-	1/3/0	-	-	-	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	-	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	1/3/0	-	-	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	3/9/0	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	1/3/0	-	-	-	3/18/0	1/6/0	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	1/30/0	-	-	-	3/90/0	3/90/0	-	-	1/30/0

- QBS: Qual By Similarity
- Qual Device OP07CDR is qualified at MSL1 260C
- Qual Device OP07CP is qualified at NOT CLASSIFIED NOT CLASSIFIED

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2208-083

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: OP07CDR	QBS Process Reference: LM2902BQPWRQ1	QBS Process Reference: TL431BQDBZR	QBS Package Reference: OPA4991QDRQ1	QBS Package Reference: TMP1075DR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0	3/231/0
UHA	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	-
UHA	A3	Unbiased HAST	110C/85%RH	264 Hours	-	3/231/0	-	-	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0	-
HTOL	B1	Life Test	150C	300 Hours	1/77/0	-	3/231/0	-	-
HTOL	B1	Life Test	150C	408 Hours	-	3/231/0	-	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	3/9/0	-	1/3/0	1/3/0

Type	#	Test Name	Condition	Duration	Qual Device: OP07CDR	QBS Process Reference: LM2902BQPWRQ1	QBS Process Reference: TL431BQDBZR	QBS Package Reference: OPA4991QDRQ1	QBS Package Reference: TMP1075DR
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	3/9/0	1/3/0	-	-
ESD	E2	ESD HBM	-	4000 Volts	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	3/18/0	1/6/0	1/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	3/90/0	3/90/0	-

- QBS: Qual By Similarity
- Qual Device OP07CDR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2210-011

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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